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(54) Title: METHOD AND APPARATUS FOR COPPER PLATING USING ELECTROLESS PLATING AND ELECTROPLATING

(57) Abstract

A reactor (20) for plating a metal onto a surface of a workpiece (25) is set forth. The reactor (20) comprises a reactor bowl (35) including an electroplating solution disposed therein and an anode (55) disposed in the reactor bowl in contact with the electroplating solution. A contact assembly (85) is spaced from the anode (55) within the reactor bowl (35). The contact assembly includes a plurality of contacts (not shown) disposed to contact a peripheral edge of the surface of the workpiece to provide electroplating power to the workpiece. The contacts, which may be in the form of a Belleville ring or discreet flexures, execute wiping action against the workpiece surface as the workpiece is brought into contact therewith. The contact assembly also includes a barrier (not shown) disposed interior of the plurality of contacts.

